

ABSTRACT

A wafer supported by a carrier is provided where a bonding layer and an extendable film are disposed in between the carrier and the wafer. Then, a photoresist pattern is formed on a surface of the wafer to define scribe lines of the wafer. Following that, an anisotropic etching process is performed to remove the wafer uncovered by the photoresist pattern to form a plurality of dies. Finally the bonding layer is separated from the carrier.